



Material Content Data Sheet



Sales Product Name				IPB160N04S4L-H1		Issued		1. August 2018	
MA#				MA001104548					
Package				PG-TO263-7-3		Weight*		1524.36 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.138	0.34	0.34	3370	3370	
leadframe	inorganic material	phosphorus	7723-14-0	0.241	0.02		158		
	non noble metal	iron	7439-89-6	0.803	0.05		527		
	non noble metal	copper	7440-50-8	801.714	52.58	52.65	525934	526619	
	non noble metal	aluminium	7429-90-5	11.346	0.74	0.74	7443	7443	
wire	non noble metal	aluminium	7429-90-5	11.346	0.74	0.74	7443	7443	
encapsulation	organic material	carbon black	1333-86-4	8.733	0.57		5729		
	plastics	epoxy resin	-	96.068	6.30		63022		
	inorganic material	silicondioxide	60676-86-0	477.428	31.32	38.19	313199	381950	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8080	8080	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.269	0.02	0.02	177	178	
solder	non noble metal	tin	7440-31-5	0.079	0.01		52		
	noble metal	silver	7440-22-4	0.099	0.01		65		
	non noble metal	lead	7439-92-1	3.776	0.25	0.27	2477	2594	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		70		
	non noble metal	copper	7440-50-8	106.210	6.97	6.98	69675	69766	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com